# **4-Bit Magnitude Comparator**

The MC14585B 4–Bit Magnitude Comparator is constructed with complementary MOS (CMOS) enhancement mode devices. The circuit has eight comparing inputs (A3, B3, A2, B2, A1, B1, A0, B0), three cascading inputs (A < B, A = B, and A > B), and three outputs (A < B, A = B, and A > B). This device compares two 4–bit words (A and B) and determines whether they are "less than", "equal to", or "greater than" by a high level on the appropriate output. For words greater than 4–bits, units can be cascaded by connecting outputs (A > B), (A < B), and (A = B) to the corresponding inputs of the next significant comparator. Inputs (A < B), (A = B), and (A > B) on the least significant (first) comparator are connected to a low, a high, and a low, respectively.

Applications include logic in CPU's, correction and/or detection of instrumentation conditions, comparator in testers, converters, and controls.

#### Features

- Diode Protection on All Inputs
- Expandable
- Applicable to Binary or 8421–BCD Code
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–Power TTL Loads or One Low–Power Schottky TTL Load over the Rated Temperature Range
- Can be Cascaded See Figure 3
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V <sub>DD</sub>	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V <sub>in</sub> , V <sub>out</sub>	– 0.5 to V <sub>DD</sub> + 0.5	V
Input or Output Current (DC or Transient) per Pin	I <sub>in</sub> , I <sub>out</sub>	±10	mA
Power Dissipation per Package (Note 1)	PD	500	mW
Ambient Temperature Range	T <sub>A</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C
Lead Temperature (8-Second Soldering)	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic "P and D/DW"

Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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#### MARKING DIAGRAMS

	PDIP-16 P SUFFIX CASE 648	16 <b>հՃՃՃՃՃՃՃ</b> MC14585BCP o AWLYYWWG 177777777777777777777777777777777777
1	SOIC-16 D SUFFIX CASE 751B	16 14585BG  1
The AMAGENT	SOEIAJ-16 F SUFFIX CASE 966	16 MC14585B ALYWG 1
A WL I	= Assembly = Wafer I o	

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G = Pb-Free Package

#### **ORDERING INFORMATION**

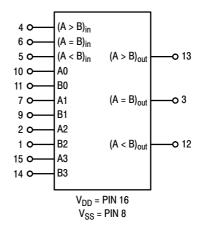
Device	Package	Shipping <sup>†</sup>
MC14585BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14585BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14585BDR2G	SOIC-16 (Pb-Free)	2500/Tape & Reel
MC14585BFELG	SOEIAJ-16 (Pb-Free)	2000/Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### **PIN ASSIGNMENT**

B2 [	1•	16	V <sub>DD</sub>
A2 [	2	15	] A3
(A = B) <sub>out</sub> [	3	14	] B3
(A > B) <sub>in</sub> [	4	13	] (A > B) <sub>out</sub>
(A < B) <sub>in</sub> [	5	12	] (A < B) <sub>out</sub>
(A = B) <sub>in</sub> [	6	11	] во
A1 [	7	10	] A0
v <sub>ss</sub> [	8	9	] B1
L			•

#### **BLOCK DIAGRAM**



TRUTH	TABLE	(x = Don <sup>*</sup>	't Care)

	Inputs								
	Comp	Comparing Cascading Outputs					1		
A3, B3	A2, B2	A1, B1	A0, B0	A < B	A = B	A > B	A < B	A = B	A > B
A3 > B3	х	х	х	х	х	х	0	0	1
A3 = B3	A2 > B2	х	х	х	х	х	0	0	1
A3 = B3	A2 = B2	A1 > B1	х	х	х	х	0	0	1
A3 = B3	A2 = B2	A1 = B1	A0 > B0	х	х	х	0	0	1
A3 = B3	A2 = B2	A1 = B1	A0 = B0	0	0	х	0	0	1
A3 = B3	A2 = B2	A1 = B1	A0 = B0	0	1	х	0	1	0
A3 = B3	A2 = B2	A1 = B1	A0 = B0	1	0	х	1	0	0
A3 = B3	A2 = B2	A1 = B1	A0 = B0	1	1	х	1	1	0
A3 = B3	A2 = B2	A1 = B1	A0 < B0	х	х	х	1	0	0
A3 = B3	A2 = B2	A1 < B1	х	х	х	х	1	0	0
A3 = B3	A2 < B2	х	х	х	х	х	1	0	0
A3 < B3	х	х	х	х	Х	Х	1	0	0

<b>ELECTRICAL CHARACTERISTICS</b>	(Voltages Referenced to V <sub>SS</sub> )
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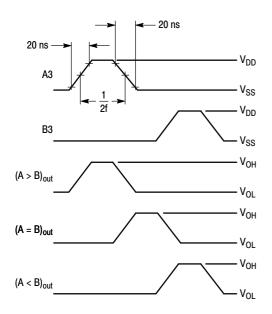
			- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage "0" Level V <sub>in</sub> = V <sub>DD</sub> or 0	V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
"1" Level V <sub>in</sub> = 0 or V <sub>DD</sub>	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95		4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95	- -	Vdc
Input Voltage "0" Level $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	VIL	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" Level (V <sub>O</sub> = 0.5 or 4.5 Vdc) (V <sub>O</sub> = 1.0 or 9.0 Vdc) (V <sub>O</sub> = 1.5 or 13.5 Vdc)	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11		Vdc
$\begin{array}{l} \mbox{Output Drive Current} \\ (V_{OH} = 2.5 \mbox{ Vdc}) \\ (V_{OH} = 4.6 \mbox{ Vdc}) \\ (V_{OH} = 9.5 \mbox{ Vdc}) \\ (V_{OH} = 13.5 \mbox{ Vdc}) \end{array}$	I <sub>ОН</sub>	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2		- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8		- 1.7 - 0.36 - 0.9 - 2.4		mAdc
$\begin{array}{ll} (V_{OL} = 0.4 \; Vdc) & Sink \\ (V_{OL} = 0.5 \; Vdc) \\ (V_{OL} = 1.5 \; Vdc) \end{array}$	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	l <sub>in</sub>	15	-	±0.1	-	$\pm 0.00001$	±0.1	-	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	-	-	-	-	5.0	7.5	_	-	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0 10 15	- - -	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Notes 3, 4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	Ι <sub>Τ</sub>	5.0 10 15			$I_{T} = ($	).6 μΑ/kHz) f 1.2 μΑ/kHz) f 1.8 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF: I<sub>T</sub>(C<sub>L</sub>) = I<sub>T</sub>(50 pF) + (C<sub>L</sub> - 50) Vfk where: I<sub>T</sub> is in µA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.001.

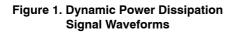
### SWITCHING CHARACTERISTICS (Note 5) (C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25 $^{\circ}$ C)

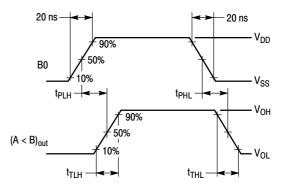
Characteristic	Symbol	V <sub>DD</sub>	Min	<b>Typ</b> (Note 6)	Max	Unit
Output Rise and Fall Time $t_{TLH}$ , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	- - -	100 50 40	200 100 80	ns
Turn–On, Turn–Off Delay Time $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 345 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 147 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 105 \text{ ns}$	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15		430 180 130	860 360 260	ns

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



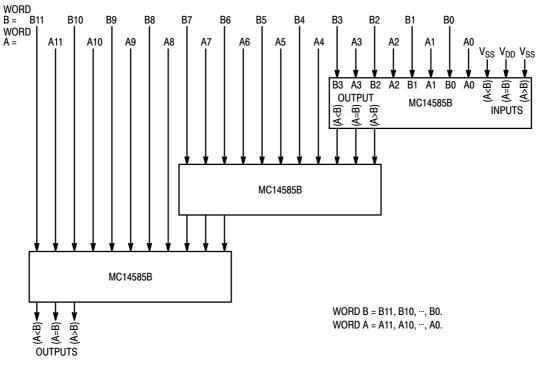
Inputs (A>B) and (A=B) high, and inputs B2, A2, B1, A1, B0, A0 and (A<B) low. f in respect to a system clock.





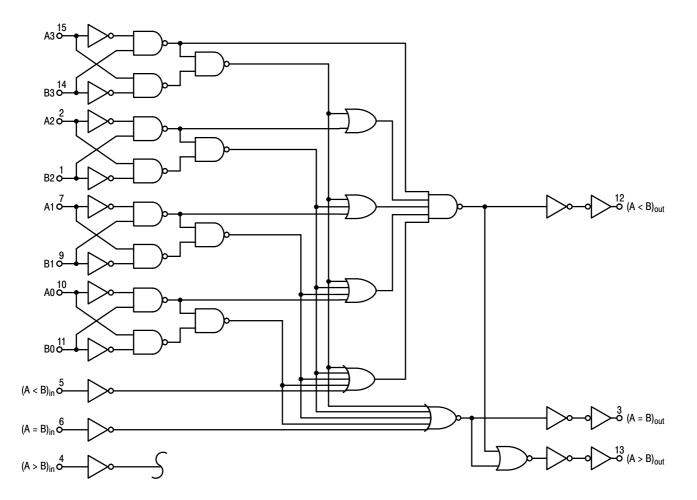
Inputs (A>B) and (A=B) high, and inputs B3, A3, B2, A2, B1, A1, A0, and (A<B) low.

### Figure 2. Dynamic Signal Waveforms



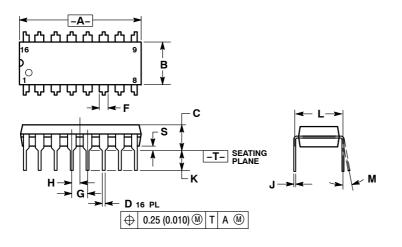


### LOGIC DIAGRAM



#### PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 **ISSUE T** 



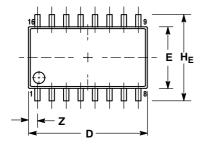
NOTES:

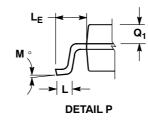
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 4. DIMENSION B DOES NOT INCLUDE MOLD ELADUL

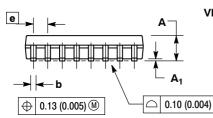
- MOLD FLASH. 5. ROUNDED CORNERS OPTIONAL.

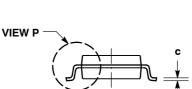
	INC	HES	MILLIN	IETERS
DIM	MIN MAX		MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54 BSC	
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
κ	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SOEIAJ-16 CASE 966-01 **ISSUE A** 









NOTES:

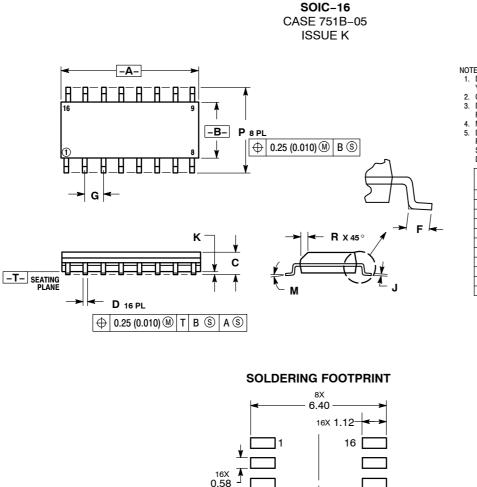
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS D AND DE DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR DODTINGIONS GUINE. MOLT PERSENT DIMENSIONING AND TOLERANCING PER ANSI

  - OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE INCLODE DAMBAR PROTINGSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE COB (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	) BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
Μ	0 °	10 °	0 °	10 °
Q1	0.70	0.90	0.028	0.035
Z		0.78		0.031

#### PACKAGE DIMENSIONS



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PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIMENSION AT MAXIMUM MATERIAL COND							
	MILLIN	IETERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
Α	9.80	10.00	0.386	0.393			
В	3.80	4.00	0.150	0.157			
С	1.35	1.75	0.054	0.068			
D	0.35	0.49	0.014	0.019			
F	0.40	1.25	0.016	0.049			
G	1.27	1.27 BSC		) BSC			
J	0.19	0.25	0.008	0.009			
Κ	0.10	0.25	0.004	0.009			
Μ	0 °	7°	0 °	7°			
Ρ	5.80	6.20	0.229	0.244			
R	0.25	0.50	0.010	0.019			

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